Vishay Semiconductors

Half Bridge IGBT Power Module, 1200 V, 100 A



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INT-A-PAK

PRODUCT SUMMARY					
V _{CES}	1200 V				
I_C at T_C = 80 °C	100 A				
V _{CE(on)} (typical) at I _C = 100 A, 25 °C	1.90 V				
Speed	8 kHz to 30 kHz				
Package	INT-A-PAK				
Circuit	Half bridge				

FEATURES

- Low V_{CE(sat)} trench IGBT technology
- 10 µs short circuit capability
- V_{CE(sat)} with positive temperature coefficient
- Maximum junction temperature 175 °C
- Low inductance case
- · Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATIONS

- UPS (Uninterruptable Power Supply)
- Inverter for motor drive
- AC and DC servo drive amplifier

DESCRIPTION

Vishay's IGBT power module provides ultra low conduction loss as well as short circuit ruggedness. It is designed for applications such as general inverters and UPS.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \text{ °C}$ unless otherwise noted)				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V _{CES}		1200	V
Gate to emitter voltage	V _{GES}		± 30	v
Collector current		T _C = 25 °C	180	
	I _C	T _C = 80 °C	100	
Pulsed collector current	I _{CM} ⁽¹⁾	t _p = 1 ms	200	А
Diode continuous forward current	I _F	T _C = 80 °C	100	
Diode maximum forward current	I _{FM} ⁽¹⁾	t _p = 1 ms	200	
Maximum power dissipation	PD	T _J = 175 °C	652	W
Short circuit withstand time	t _{SC}	T _C = 125 °C	10	μs
RMS isolation voltage	V _{ISOL}	f = 50 Hz, t = 1 min	4000	V

Note

⁽¹⁾ Repetitive rating: pulse width limited by maximum junction temperature.

IGBT ELECTRICAL SPECIFICATIONS ($T_c = 25 \text{ °C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	V _{(BR)CES}	T _J = 25 °C	1200	-	-	
Collector to emitter saturation voltage	V _{CE(sat)}	V_{GE} = 15 V, I_{C} = 100 A, T_{J} = 25 °C	-	1.90	2.35	v
		V_{GE} = 15 V, I_{C} = 100 A, T_{J} = 175 °C	-	2.50	-	
Gate to emitter threshold voltage	V _{GE(th)}	V_{CE} = V_{GE} , I_C = 5.0 mA, T_J = 25 °C	5.0	5.9	7.5	
Collector cut-off current	I _{CES}	$V_{CE} = V_{CES}, V_{GE} = 0 \text{ V}, \text{ T}_{J} = 25 ^{\circ}\text{C}$	-	-	5.0	mA
Gate to emitter leakage current	I _{GES}	$V_{GE} = V_{GES}$, $V_{CE} = 0$ V, $T_J = 25$ °C	-	-	400	nA

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COMPLIANT





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SWITCHING CHARACTERISTICS						
PARAMETER SY		TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t _{d(on)}		-	187	-	ns mJ
Rise time	t _r		-	57	-	
Turn-off delay time	t _{d(off)}	V_{CC} = 600 V, I _C = 100 A, R _q = 5.6 Ω,	-	180	-	
Fall time	t _f	$V_{GE} = \pm 15 \text{ V}, \tilde{T}_{J} = 25 \text{ °C}$	-	149	-	
Turn-on switching loss	E _{on}		-	4.97	-	
Turn-off switching loss	E _{off}		-	4.69	-	
Turn-on delay time	t _{d(on)}		-	189	-	- ns
Rise time	t _r		-	58	-	
Turn-off delay time	t _{d(off)}	V_{CC} = 600 V, I _C = 100 A, R _g = 5.6 Ω,	-	187	-	
Fall time	t _f	$V_{GE} = \pm 15 \text{ V}, \text{ T}_{J} = 125 \text{ °C}^{\circ}$	-	220	-	
Turn-on switching loss	E _{on}		-	7.80	-	
Turn-off switching loss	E _{off}		-	5.85	-	mJ
Input capacitance	C _{ies}		-	12.8	-	
Output capacitance	C _{oes}	$V_{GE} = 0 V$, $V_{CE} = 30 V$, f = 1.0 MHz	-	0.46	-	nF
Reverse transfer capacitance	C _{res}		-	0.32	-	
SC data	I _{SC}	$\begin{array}{l} t_p \leq 10 \; \mu \text{s}, V_{GE} = 15 \; \text{V}, T_J = 125 \; ^\circ \text{C}, \\ V_{CC} = 900 \; \text{V}, V_{CEM} \leq 1200 \; \text{V} \end{array}$	-	890	-	А
Stray inductance	L _{CE}		-	-	30	nH
Module lead resistance, terminal to chip	R _{CC'+EE'}		-	0.75	-	mΩ

DIODE ELECTRICAL SPECIFICATIONS ($T_C = 25 \text{ °C}$ unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Forward voltage	V _F	I _F = 100 A	T _J = 25 °C	-	1.82	2.20	v
Forward voltage			T _J = 125 °C	-	1.95	-	
Reverse recovery charge	Q _{rr}	I _F = 100 A, V _R = 600 V, R _G = 5.6 Ω V _{GE} = -15 V	T _J = 25 °C	-	8.1	-	μC
			T _J = 125 °C	-	14.0	-	
Peak reverse recovery current	I _{rr}		T _J = 25 °C	-	81	-	А
			T _J = 125 °C	-	98	-	A
Reverse recovery energy	E _{rec}		T _J = 25 °C	-	2.99	-	mJ
			T _J = 125 °C	-	4.85	-	IIIJ

THERMAL AND MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction temperature		TJ		-	-	175	°C
Storage temperature range		T _{Stg}		-40	-	125	°C
Junction to case	IGBT	- R _{thJC}		-	-	0.23	
per ½ module	Diode			-	-	0.36	K/W
Case to sink (Conductive greas	e applied)	R _{thCS}		-	0.05	-	
Mounting torque			Power terminal screw: M5	2.5 to 5.0		Nm	
			Mounting screw: M6	;	3.0 to 5.0	C	INITI
Weight			Weight of module	-	150	-	g

Revision: 11-Jun-15 For technical questions within your region: <u>DiodesA</u> Document Number: 93800

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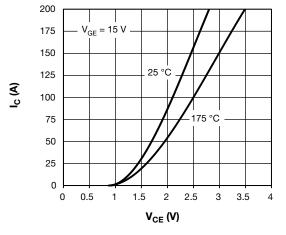


Fig. 1 - IGBT Typical Output Characteristics

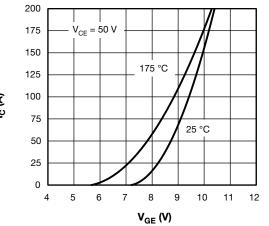


Fig. 2 - IGBT Transfer Characteristics

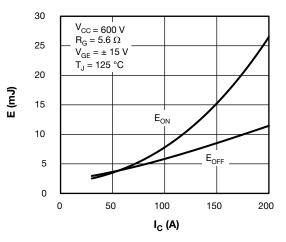


Fig. 3 - IGBT Switching Loss vs. I_C

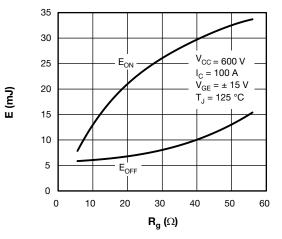
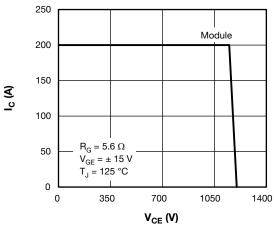


Fig. 4 - IGBT Switching Loss vs. R_G





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Ic (A)

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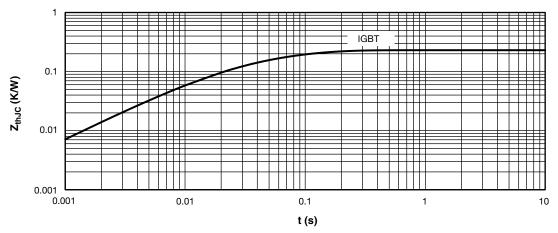
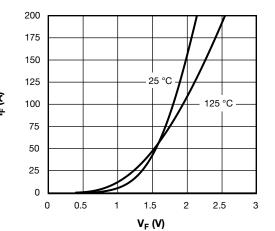


Fig. 6 - IGBT Transient Thermal Impedance



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Fig. 7 - Diode Forward Characteristics

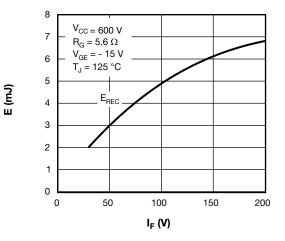
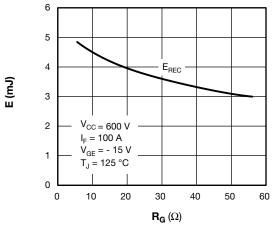


Fig. 8 - Diode Switching Loss vs. I_F





I_F (A)

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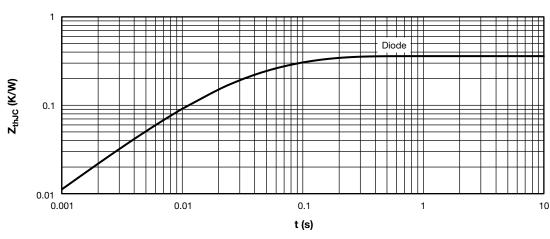
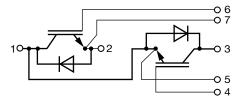


Fig. 10 - Diode Transient Thermal Impedance

CIRCUIT CONFIGURATION

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LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95524			

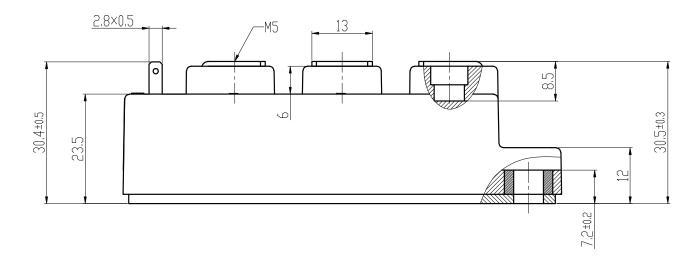
Outline Dimensions

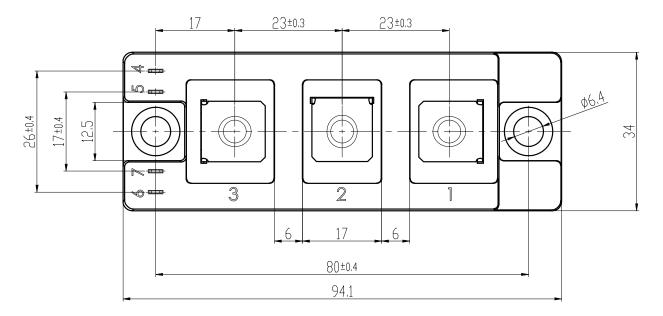


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DIMENSIONS in millimeters (inches)







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